

HSC88

Silicon Schottky Barrier Diode for Various Detector, Mixer

REJ03G0624-0100
(Previous: ADE-208-826)
Rev.1.00
Apr 12, 2005

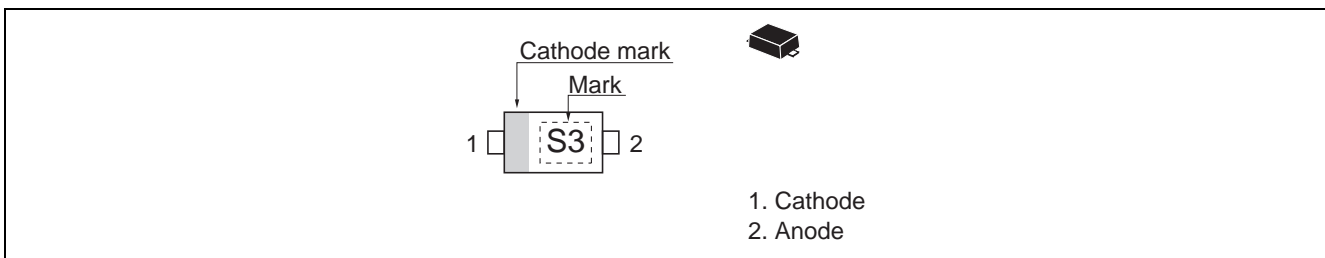
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward voltage.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
HSC88	S3	UFP	PWSF0002ZA-A (UFP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I_O	15	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	0.350	—	0.420	V	$I_F = 1 \text{ mA}$
	V_{F2}	0.500	—	0.580		$I_F = 10 \text{ mA}$
Reverse current	I_{R1}	—	—	0.2	μA	$V_R = 2 \text{ V}$
	I_{R2}	—	—	10		$V_R = 10 \text{ V}$
Capacitance	C	—	—	0.80	pF	$V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$
ESD-Capability *1	—	30	—	—	Ω	C = 200 pF, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion ; $I_R \geq 0.4 \mu\text{A}$ at $V_R = 2 \text{ V}$

Main Characteristic

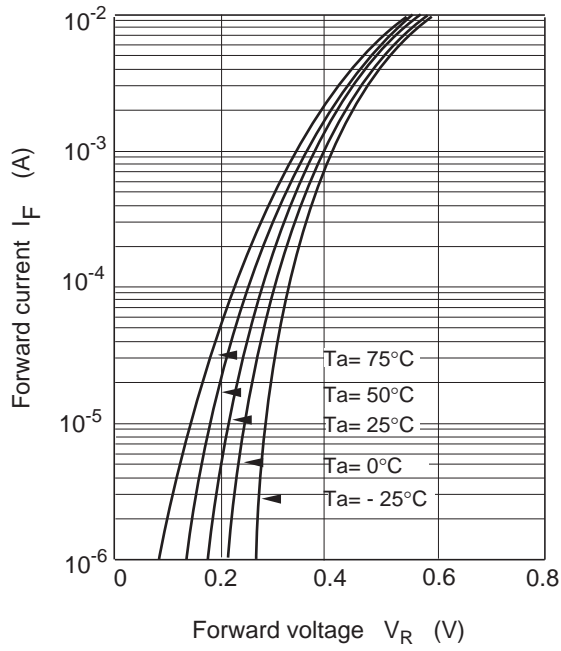


Fig.1 Forward current vs. Forward voltage

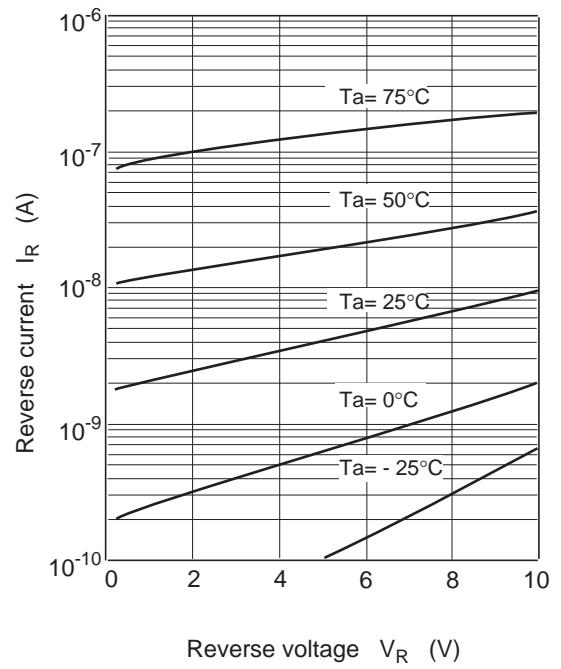


Fig.2 Reverse current vs. Reverse voltage

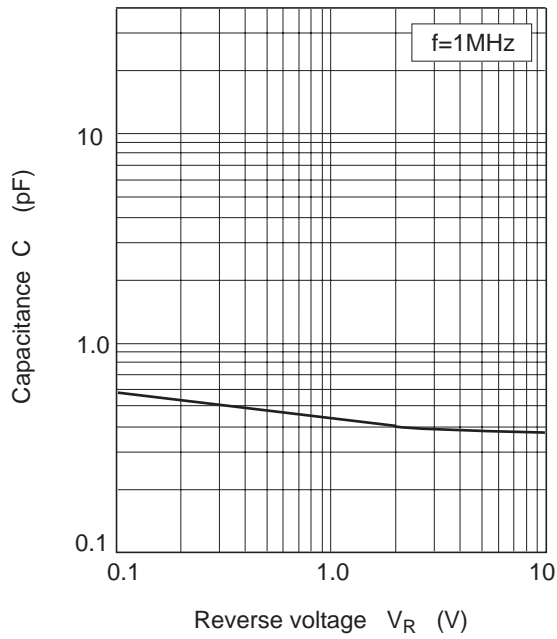
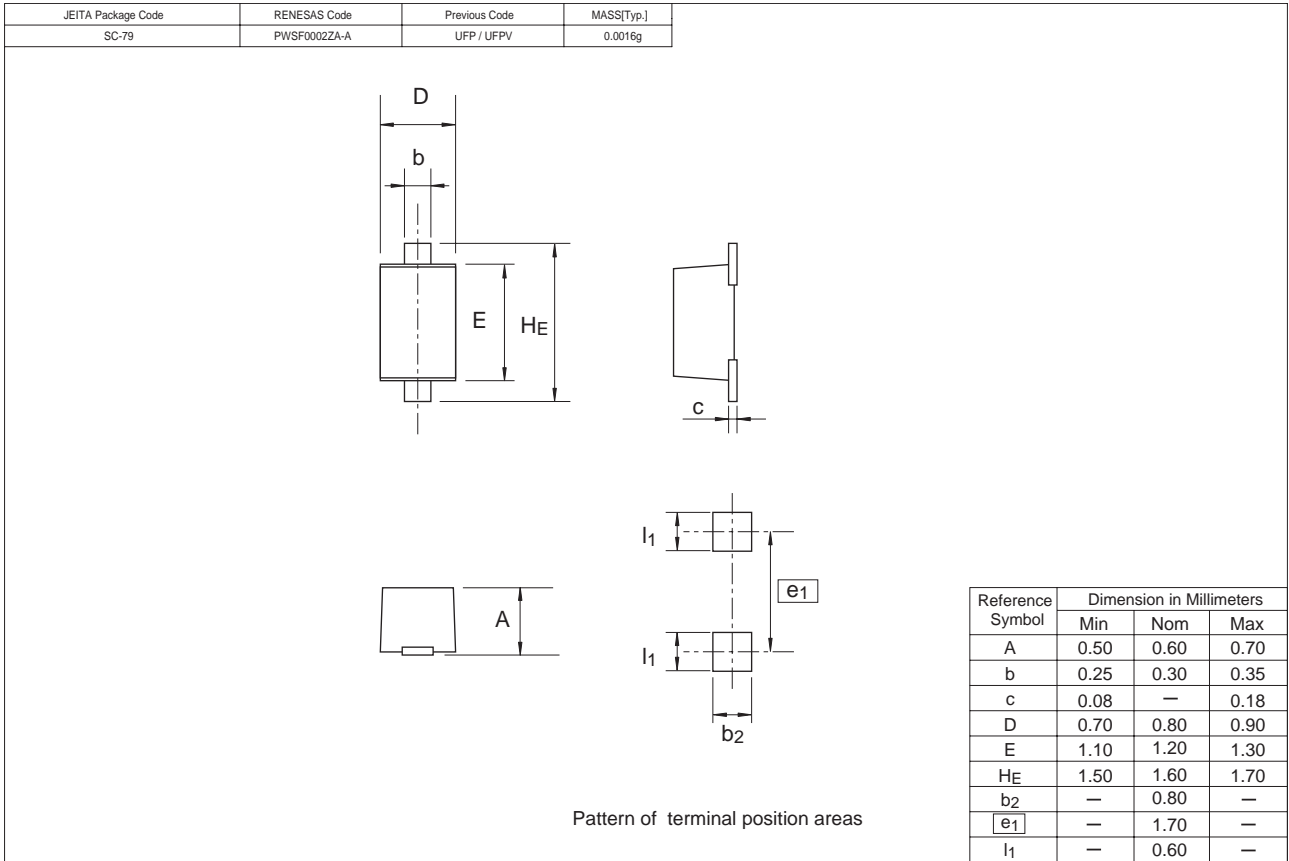


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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